

DERWENT-ACC-NO: 1988-143028
DERWENT-WEEK: 198821
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TITLE: Lead shaping apparatus for semiconductor devices -
has die holder
including cam die for bending IC leads and push pin for die
cam, and punch
holder with cam punch NoAbstract Dwg 1/5

PATENT-ASSIGNEE: TOSHIBA KK[TOKE]

PRIORITY-DATA: 1986JP-0227972 (September 29, 1986)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
JP 63084056 A	April 14, 1988	N/A
005	N/A	

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP63084056A	N/A	1986JP-0227972
September 29, 1986		

INT-CL_(IPC): B21D005/01; H01L023/50

ABSTRACTED-PUB-NO:

EQUIVALENT-ABSTRACTS:

TITLE-TERMS:

LEAD SHAPE APPARATUS SEMICONDUCTOR DEVICE DIE HOLD CAM DIE
BEND IC LEAD PUSH
PIN DIE CAM PUNCH HOLD CAM PUNCH NOABSTRACT

DERWENT-CLASS: P52 U11

EPI-CODES: U11-E02B;

L Number	Hits	Search Text	DB	Time stamp
1	117	(warped or curved or concave or convex) adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 15:14
2	7	((warped or curved or concave or convex) adj chip) and (semiconductor adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 15:14
3	781	(warped or curved or concave or convex) adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:33
4	7	((warped or curved or concave or convex) adj chip) and (semiconductor adj chip)) and (semiconductor adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 15:15
5	14	((warped or curved or concave or convex) adj substrate) and (semiconductor adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:09
6	0	(satcked adj chip) near density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:09
7	1	(stacked adj chip) near density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:10
9	13	(stacked adj chips) with density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:10
8	11	(stacked adj chip) with density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:21
10	29	(stacked adj chip) same density	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:21
11	18	((stacked adj chip) same density) not ((stacked adj chip) with density)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:23
12	223	(warped or curved or concave or convex or curving or bending) adj chip	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:48
13	110	((warped or curved or concave or convex or curving or bending) adj chip) and (method or process)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:35
14	44	((warped or curved or concave or convex or curving or bending) adj chip) and (holder or clamp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:47

15	9	((warped or curved or concave or convex or curving or bending) adj chip) and (holder or clamp)) and ((warped or curved or concave or convex or curving or bending) with (holder or clamp))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:50
16	19824	(chip or die) with (holder or clamp)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:52
17	4084	((chip or die) with (holder or clamp)) and (curve or bend or bending or concave or convex)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:54
18	2158	((chip or die) with (holder or clamp)) and ((curve or bend or bending or concave or convex) with (chip or die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:55
19	197	((chip or die) with (holder or clamp)) and ((curve or bend or bending or concave or convex) with (chip or die))) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/14 16:55